Docket No. 0756-2293 ORIGINALLY FILED IN THE UNITED STATES PATENT AND TRADEMARK OFFICE Patent Application of Art Unit: 2811 Tatsuya ARAO et al. Examiner: T. Tran. Serial No. 09/826,416 CERTIFICATE OF MAILING Filed: April 5, 2001 I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First SEMICONDUCTOR DEVICE AND) Class Mail in an envelope addressed to: Commissioner for Patents, Washington D.C. 2023 Lon. 7-/9-92 Washington, D.C. 20231, on MANUFACTURING METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents Washington, DC 20231

THEREOF

Sir:

For:

In accordance with the duty of disclosure as set forth in 37 C.F.R. §1.56, Applicants hereby submit the following information in conformance with 37 C.F.R. §§ 1.97 and 1.98. Pursuant to 37 C.F.R. § 1.98, a copy of each of the documents cited is enclosed.

A check in the amount of \$180 is being submitted to comply with the provisions of 37 C.F.R. § 1.97(c).

It is requested that the accompanying information disclosure statement be considered and made of record in the above-captioned application. To assist the Examiner, the documents are listed on the attached form PTO-1449. It is respectfully requested that an Examiner initialed copy of this form be returned to the undersigned.

The Commissioner is hereby authorized to charge any fees connected with this filing which may be required now, or credit any overpayment to Deposit Account No. 50-2280.

Respectfully submitted,

Eric J. Robinson Reg. No. 38,285

Robinson Intellectual Property Law Office, P.C. **PMB 955** 21010 Southbank Street Potomac Falls, Virginia 20165 (571) 434-6789

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